

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAJOR PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 10 A
$V_{RRM}$	30 V
$T_j(\text{max})$	150°C
$V_F(\text{max})$	0.40 V

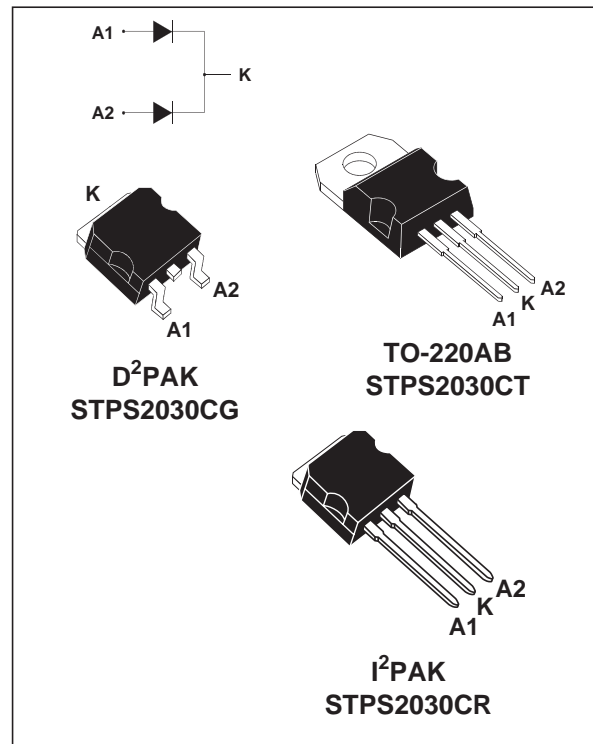
### FEATURES AND BENEFITS

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop for higher efficiency
- Low thermal resistance

### DESCRIPTION

Dual Schottky rectifier suited for switch Mode Power Supply and high frequency DC to DC converters.

Packaged in TO-220AB, D<sup>2</sup>PAK and I<sup>2</sup>PAK, this device is intended for use in low voltage high frequency inverters, free wheeling and polarity protection applications.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		30	V
$I_{F(RMS)}$	RMS forward current		30	A
$I_{F(AV)}$	Average forward current	$T_c = 140^\circ\text{C}$ $\delta = 0.5$	Per diode 20 Per device	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ Sinusoidal	180	A
$I_{RRM}$	Peak repetitive reverse current	$t_p = 2 \mu\text{s}$ square $F = 1\text{kHz}$	1	A
$I_{RSM}$	Non repetitive peak reverse current	$t_p = 100 \mu\text{s}$ square	2	A
$T_{stg}$	Storage temperature range		- 65 to + 150	°C
$T_j$	Maximum operating junction temperature *		150	°C
$dV/dt$	Critical rate of rise of reverse voltage (rated $V_R$ , $T_j = 25^\circ\text{C}$ )		10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink

## STPS2030CT/CG/CR

### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case TO-220AB - D <sup>2</sup> PAK - I <sup>2</sup> PAK	Per diode	2.2	°C/W
		Total	1.3	
$R_{th(c)}$		Coupling	0.3	°C/W

### STATIC ELECTRICAL CHARACTERISTICS (per diode)

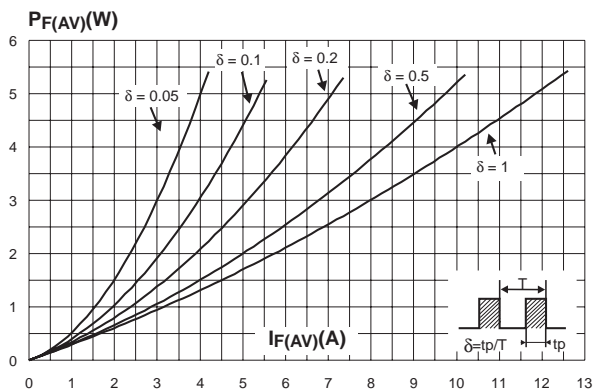
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$		0.15	1.0	mA
		$T_j = 125^\circ\text{C}$			80	160	
$V_F^*$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 10\text{ A}$		0.44	0.50	V
		$T_j = 125^\circ\text{C}$	$I_F = 10\text{ A}$		0.34	0.40	
		$T_j = 25^\circ\text{C}$	$I_F = 20\text{ A}$		0.50	0.58	
		$T_j = 125^\circ\text{C}$	$I_F = 20\text{ A}$		0.44	0.52	

Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

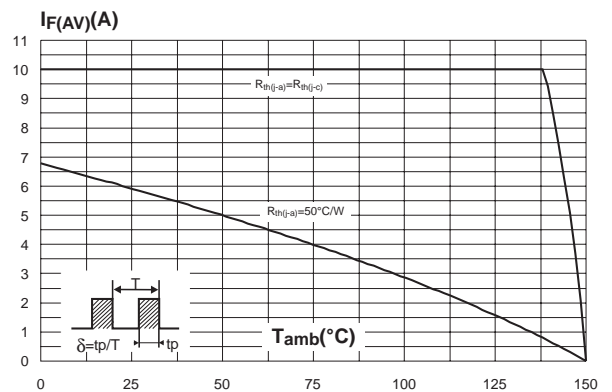
To evaluate the conduction losses use the following equation :

$$P = 0.28 \times I_{F(AV)} + 0.012 I_{F(RMS)}^2$$

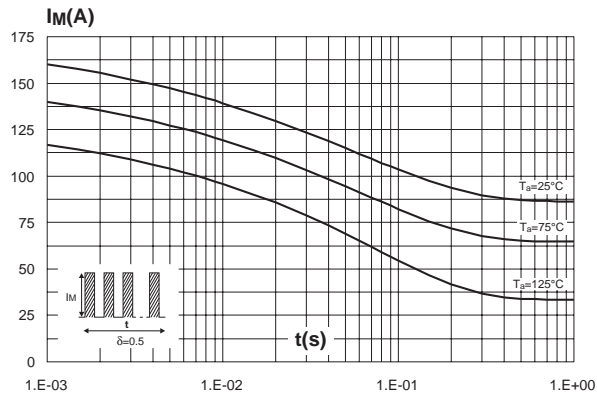
**Fig. 1:** Conduction losses versus average current.



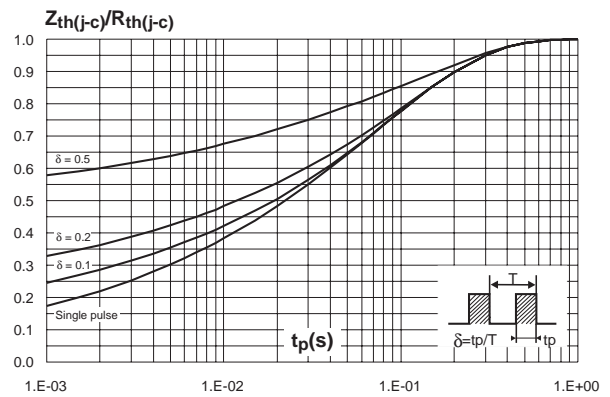
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



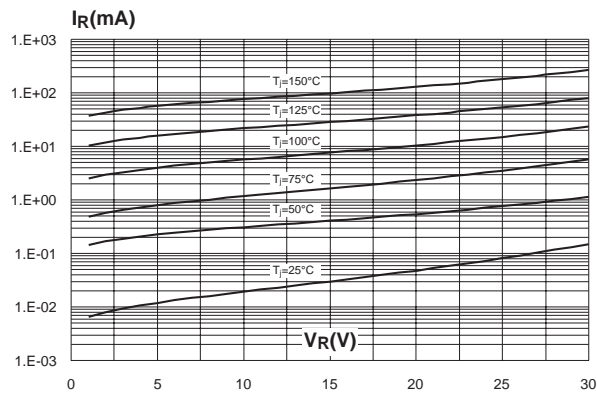
**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values).



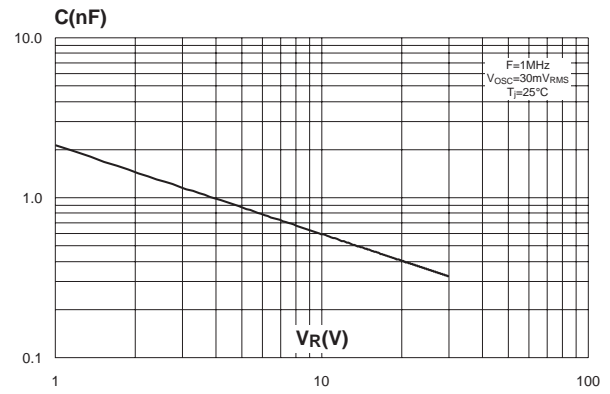
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration.



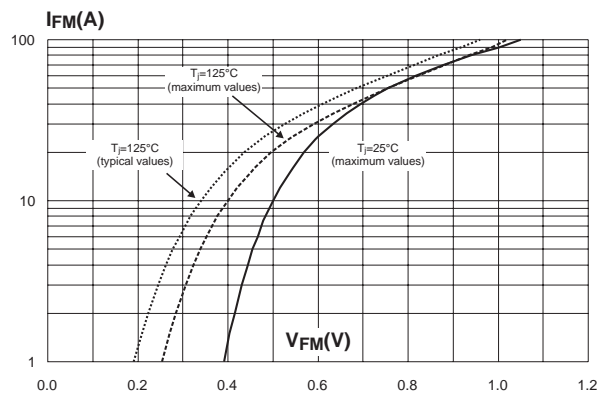
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values).



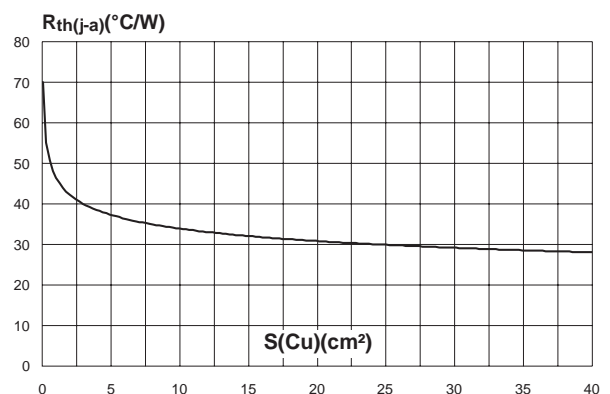
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values).



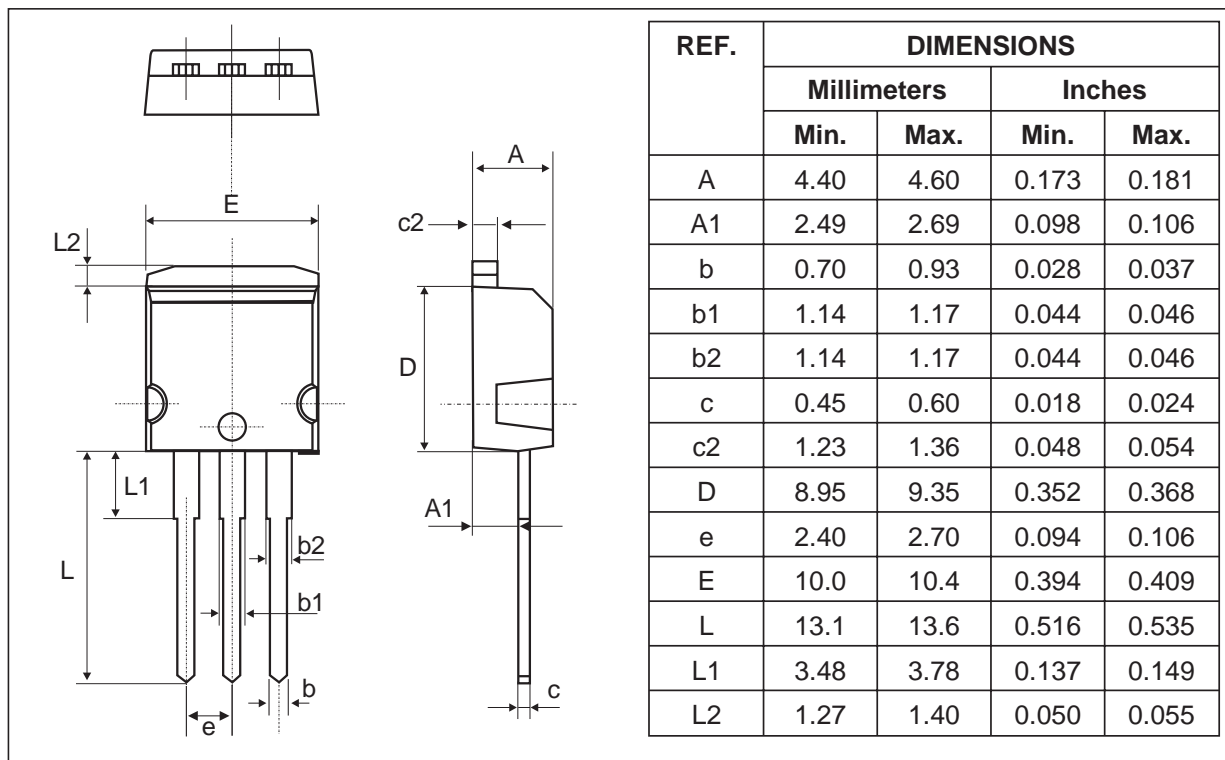
**Fig. 7:** Forward voltage drop versus forward current.



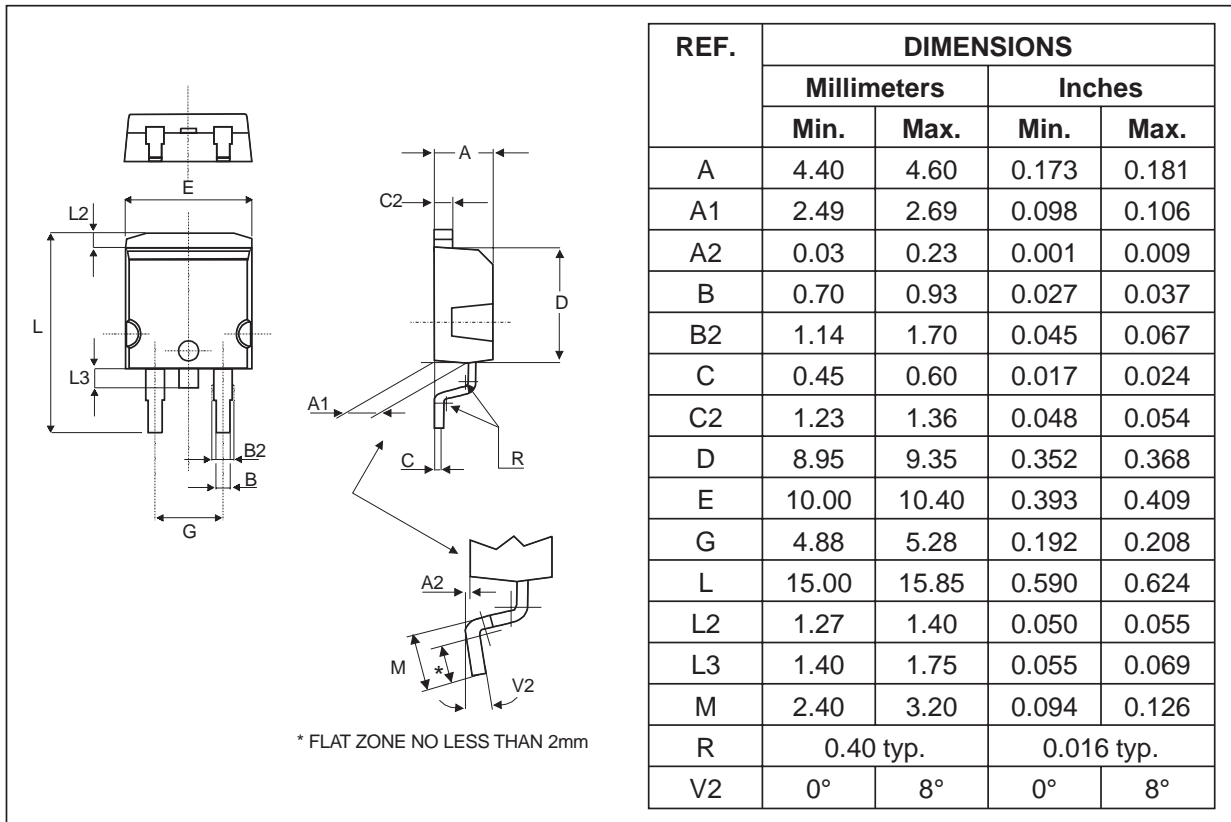
**Fig. 8:** Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu = 35μm).



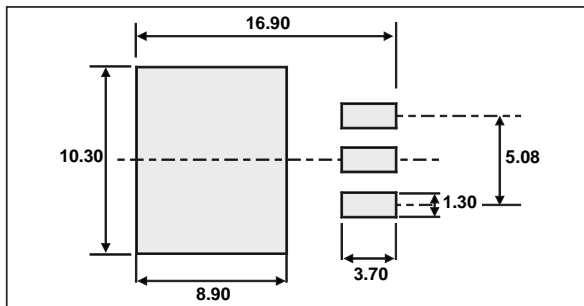
PACKAGE MECHANICAL DATA  
I<sup>2</sup>PAK



**PACKAGE MECHANICAL DATA**  
D<sup>2</sup>PAK

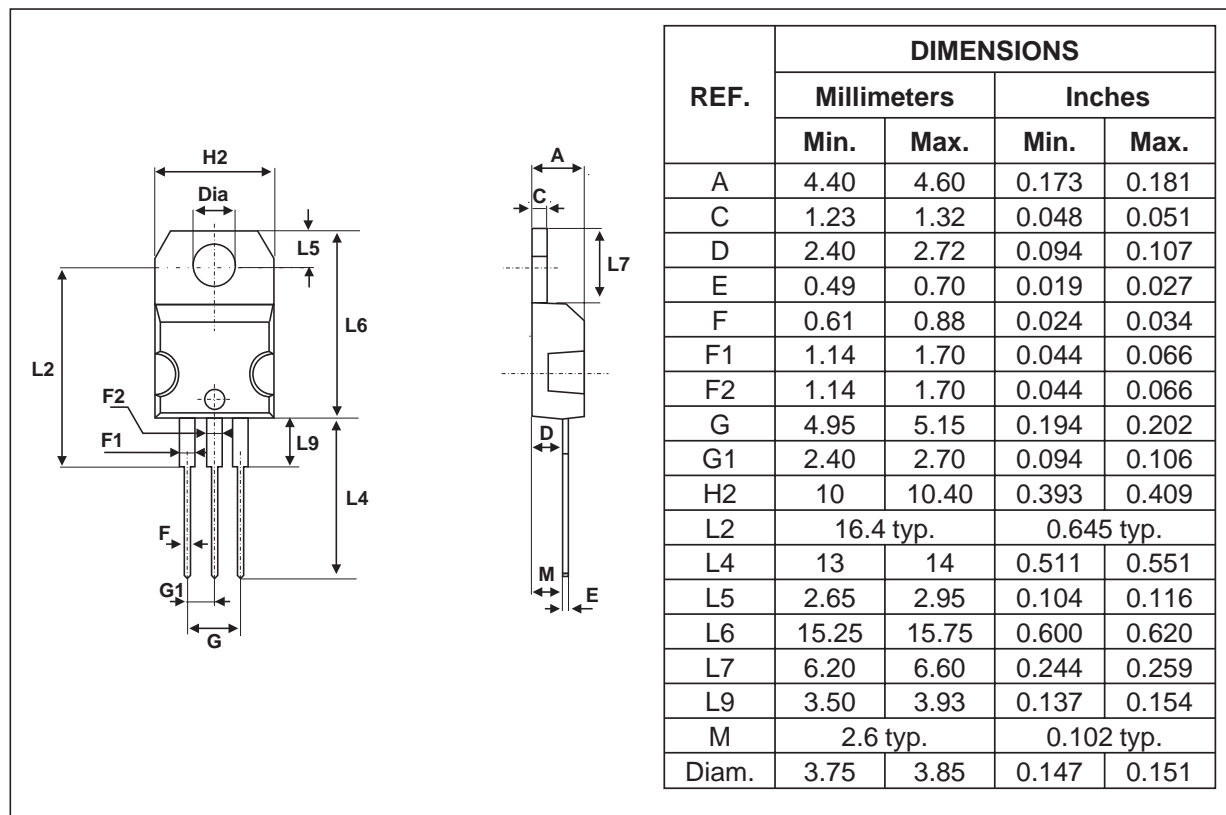


**FOOTPRINT**



# STPS2030CT/CG/CR

## PACKAGE MECHANICAL DATA TO-220AB



- Cooling method : C
- Recommended torque value : 0.55 m.N
- Maximum torque value : 0.70 m.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS2030CT	STPS2030CT	TO-220AB	2.2 g	50	Tube
STPS2030CG	STPS2030CG	D <sup>2</sup> PAK	1.48 g	50	Tube
STPS2030CG-TR	STPS2030CG	D <sup>2</sup> PAK	1.48 g	1000	Tape & reel
STPS2030CR	STPS2030CR	I <sup>2</sup> PAK	1.49 g	50	Tube

- Epoxy meets UL94,V0

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